



SOT1045-2

plastic, dual in-line compatible thermal enhanced extremely thin quad flat package; 20 terminals; 0.5 mm pitch; 4.5 mm x 2.5 mm x 0.5 mm body

3 March 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	DHXQFN20
Package type industry code	DHXQFN20
Package style descriptive code	DHXQFN (DIL-compatible thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-08-2011
Manufacturer package code	SOT1045

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.45	4.5	4.55	mm
package width	2.45	2.5	2.55	mm
seated height	-	-	0.5	mm
package height	0.38	0.4	0.42	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	20	-	



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2 Package outline

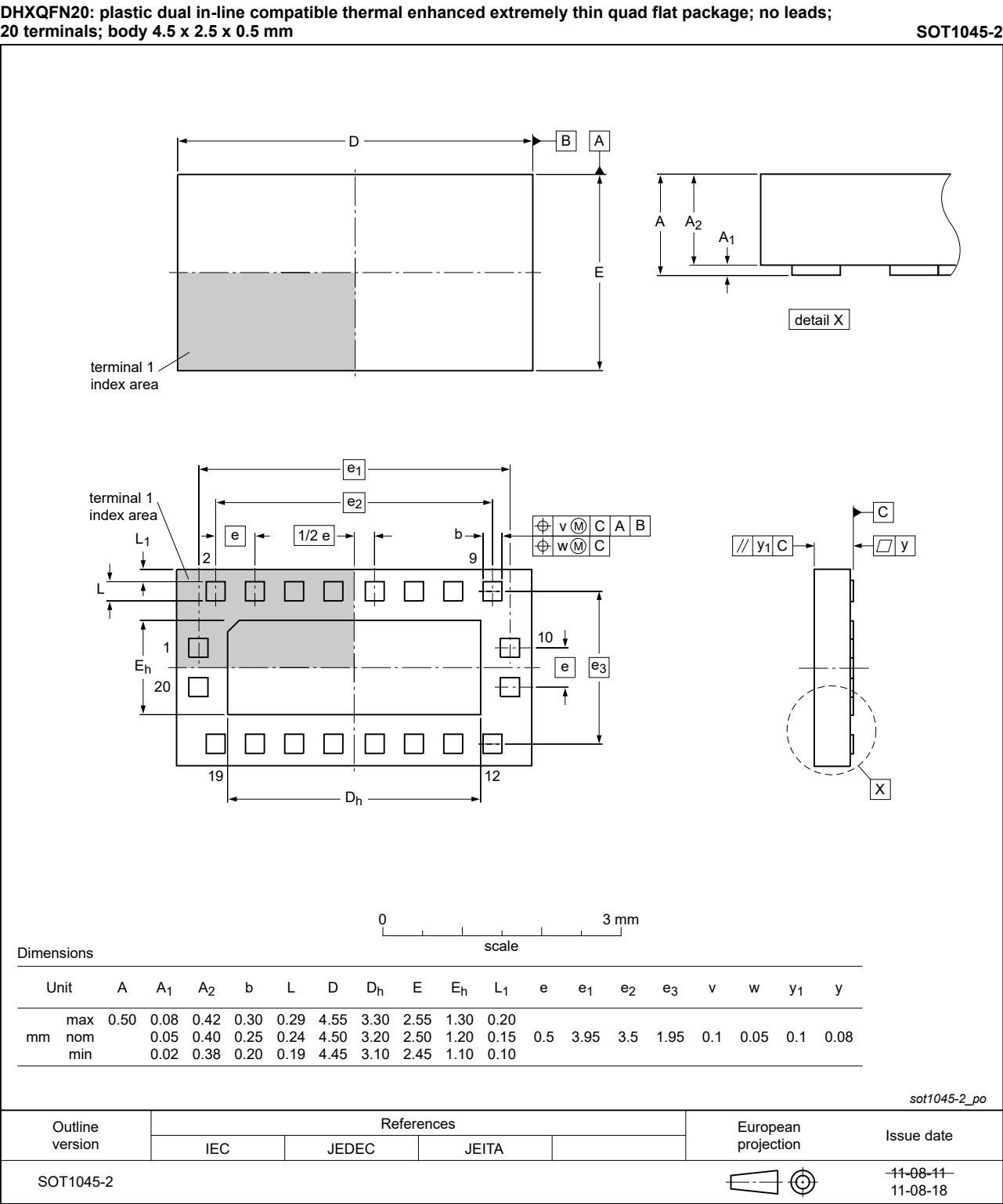


Figure 1. Package outline DHXQFN20 (SOT1045-2)

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3 Legal information

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